



ASML PAS 5000/55

Machine Number: 4111

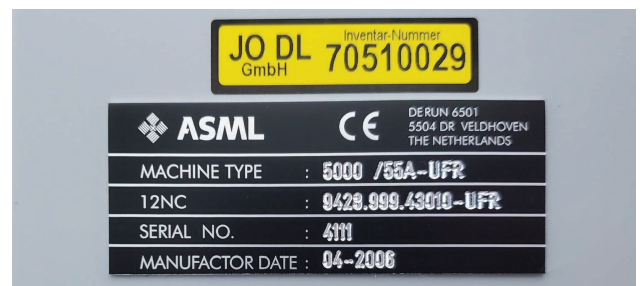
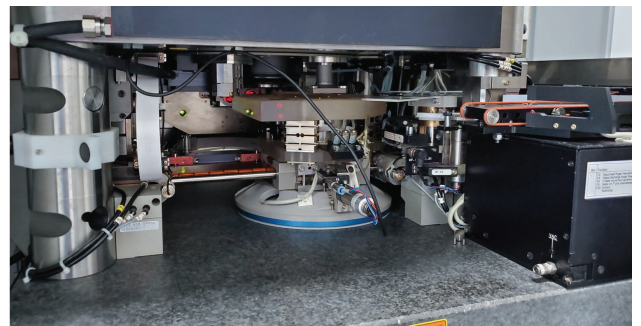
Software Release: 9.2.0

Product: ID: PAS 5000 /55

This tool is currently installed in the EOTS lab located in Vancouver WA. During the equipment qualification process, each tool is installed so engineers can replace any missing or damaged parts for the purpose of optimizing performance and recording current ATP data. Potential customers will be allowed in the EOTS lab to inspect equipment and DEMO performance for the purpose of minimizing risk during the purchase analysis process.

CONFIGURATION CM OPTIONS

PEP 2 (Color Graphics)	Y
PEP 1/3/4	Y
SECS (I/II)	Y
Reticle Error Correction	Y
Throughput Enhancement	Y
Batch Status Light	Y
88 um Error Detection	Y



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ACCEPTANCE TEST SPECIFICATIONS

Customer:					
Site:					
Machine serial number:	4111				
Model:	5000/55				
Wafer size:	3"-4"-5"-6" Wafer Compatibility				
Purchase order no:					
Software Release:	9.2.0				
Test completion date:	See notes in side-bar				
Parameter	Specification (absolute values)	FAT		SAT	
		Measured	Accept	Measured	Accept
1. Illumination					
1.1 Illumination Homogeniety					
15.0 x 15.0 mm [%]	≤2.5	1.65	10/7/2020		
9.4 x 19.0 mm [%]	≤ 3.0	1.93	10/7/2020		
Illumination intensity [mW/cm2]	≥ 550	440.6	10/7/2020		
2. Reticle masking					
2.1 Reticle masking [μm]	≤ 500	400	2/23/2021		
4. Lens distortion					
4.1 Non-correctable error [nm]					
X @15x15(nm)	≤ 120	85	2/23/2021		
Y @15x15(nm)	≤ 120	89	2/23/2021		
Mag(nm/cm)	<50	0	2/23/2021		
Die Rotation(urad)	<5	0.886	2/23/2021		
Trapezoidal X(nm/cm2)	<50	-28	2/23/2021		
Trapezoidal Y(nm/cm2)	<50	-17	2/23/2021		

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Material Handling					
5.1 Pre-alignment accuracy(Optical Sensor)					
Xm1w1 (um)	≤ 7	3	10/30/2020		
Ym1w1 (um)	≤ 7	5.5	10/30/2020		
Ym1w2 (um)	≤ 7	4.6	10/30/2020		
6. Overlay performance					
6.1 Stage repeatability					
X [nm]	≤ 100	55	2/22/2021		
Y [nm]	≤ 100	54	2/22/2021		
6.2 Single machine overlay (99.7%)					
X - Max 99.7%	≤ 150	65	2/22/2021		
Y - Max 99.7%	≤ 150	68	2/22/2021		
7. Wafer throughput					
7.1 Wafer throughput at 200 mJ/cm2	≥ 64	60.61	11/6/2020		
7.4 Reticle exchange time (seconds)	≤ 40	30.9	11/6/2020		